

30V, N-Channel NexFET™ Power MOSFETs

Check for Samples: [CSD17501Q5A](#)

FEATURES

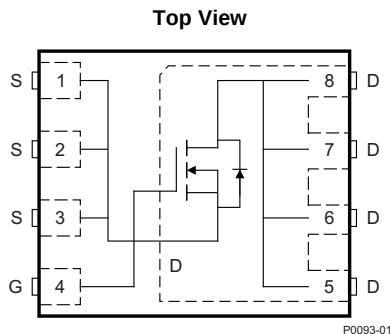
- **Ultralow Q_g and Q_{gd}**
- **Low Thermal Resistance**
- **Avalanche Rated**
- **Pb Free Terminal Plating**
- **RoHS Compliant**
- **Halogen Free**
- **SON 5-mm × 6-mm Plastic Package**

APPLICATIONS

- **Point-of-Load Synchronous Buck in Networking, Telecom, and Computing Systems**
- **Optimized for Synchronous FET Applications**

DESCRIPTION

The NexFET™ power MOSFET has been designed to minimize losses in power conversion applications.



PRODUCT SUMMARY

$T_A = 25^\circ\text{C}$ unless otherwise stated		TYPICAL VALUE		UNIT
V_{DS}	Drain to Source Voltage	30		V
Q_g	Gate Charge Total (4.5V)	13.2		nC
Q_{gd}	Gate Charge Gate to Drain	3.5		nC
$R_{DS(on)}$	Drain to Source On Resistance	$V_{GS} = 4.5\text{V}$	3	m Ω
		$V_{GS} = 10\text{V}$	2.4	m Ω
$V_{GS(th)}$	Threshold Voltage	1.3		V

ORDERING INFORMATION

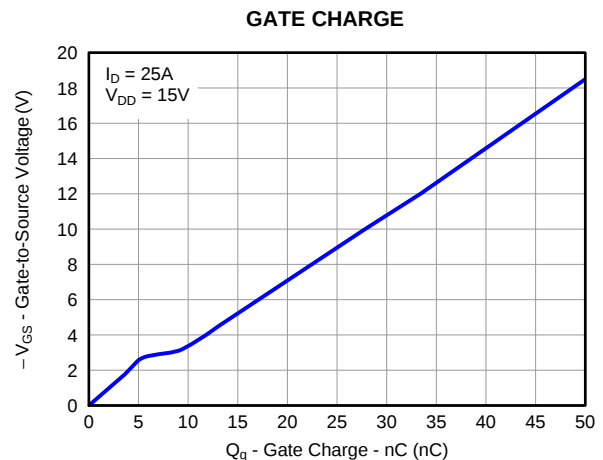
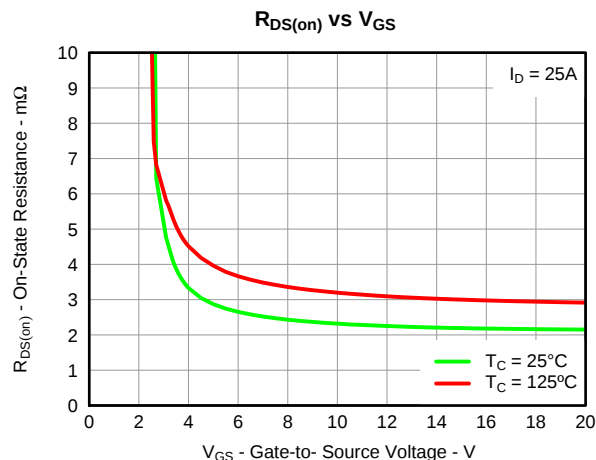
Device	Package	Media	Qty	Ship
CSD17501Q5A	SON 5-mm × 6-mm Plastic Package	13-Inch Reel	2500	Tape and Reel

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$ unless otherwise stated		VALUE	UNIT
V_{DS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	± 20	V
I_D	Continuous Drain Current, $T_C = 25^\circ\text{C}$	100	A
	Continuous Drain Current ⁽¹⁾	28	A
I_{DM}	Pulsed Drain Current, $T_A = 25^\circ\text{C}$ ⁽²⁾	187	A
P_D	Power Dissipation ⁽¹⁾	3.2	W
T_J , T_{STG}	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ\text{C}$
E_{AS}	Avalanche Energy, single pulse $I_D = 90\text{A}$, $L = 0.1\text{mH}$, $R_G = 25\Omega$	405	mJ

(1) Typical $R_{\theta JA} = 39^\circ\text{C/W}$ on a 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu pad on a 0.06-inch (1.52-mm) thick FR4 PCB.

(2) Pulse duration $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$



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NexFET is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise stated)

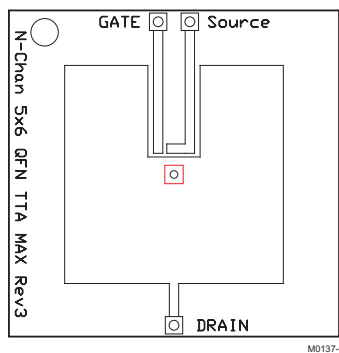
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Static Characteristics						
B _V D _{SS}	Drain to Source Voltage	V _{GS} = 0V, I _{DS} = 250μA	30			V
I _{DSS}	Drain to Source Leakage Current	V _{GS} = 0V, V _{DS} = 24V			1	μA
I _{GSS}	Gate to Source Leakage Current	V _{DS} = 0V, V _{GS} = 20V			100	nA
V _{GS(th)}	Gate to Source Threshold Voltage	V _{DS} = V _{GS} , I _{DS} = 250μA	1	1.3	1.8	V
R _{DS(on)}	Drain to Source On Resistance	V _{GS} = 4.5V, I _{DS} = 25A	3		3.7	mΩ
		V _{GS} = 10V, I _{DS} = 25A	2.4		2.9	mΩ
g _{fs}	Transconductance	V _{DS} = 15V, I _{DS} = 25A	110			S
Dynamic Characteristics						
C _{iSS}	Input Capacitance	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	2040		2630	pF
C _{oSS}	Output Capacitance		1350		1700	pF
C _{rSS}	Reverse Transfer Capacitance		66		85	pF
R _G	Series Gate Resistance		1.3		2.6	Ω
Q _g	Gate Charge Total (4.5V)	V _{DS} = 15V, I _{DS} = 25A	13.2		17	nC
Q _{gd}	Gate Charge Gate to Drain		3.5			nC
Q _{gs}	Gate Charge Gate to Source		5.4			nC
Q _{g(th)}	Gate Charge at V _{th}		2.9			nC
Q _{oSS}	Output Charge	V _{DS} = 13.7V, V _{GS} = 0V	35			nC
t _{d(on)}	Turn On Delay Time	V _{DS} = 15V, V _{GS} = 4.5V, I _{DS} = 25A, R _G = 2Ω	10.4			ns
t _r	Rise Time		17			ns
t _{d(off)}	Turn Off Delay Time		18			ns
t _f	Fall Time		7.9			ns
Diode Characteristics						
V _{SD}	Diode Forward Voltage	I _{SD} = 25A, V _{GS} = 0V	0.8		1	V
Q _{rr}	Reverse Recovery Charge	V _{DD} = 13.7V, I _F = 25A, di/dt = 300A/μs	46			nC
t _{rr}	Reverse Recovery Time		32			ns

THERMAL CHARACTERISTICS

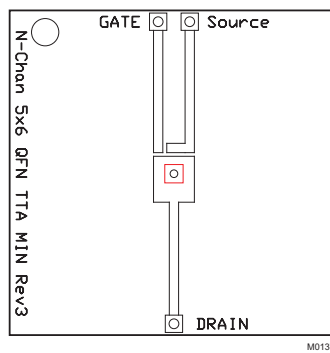
(T_A = 25°C unless otherwise stated)

PARAMETER		MIN	TYP	MAX	UNIT
R _{θJC}	Thermal Resistance Junction to Case ⁽¹⁾			1	°C/W
R _{θJA}	Thermal Resistance Junction to Ambient ⁽¹⁾⁽²⁾			49	°C/W

- (1) R_{θJC} is determined with the device mounted on a 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu pad on a 1.5-inch × 1.5-inch (3.81-cm × 3.81-cm), 0.06-inch (1.52-mm) thick FR4 PCB. R_{θJC} is specified by design, whereas R_{θJA} is determined by the user's board design.
- (2) Device mounted on FR4 material with 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu.



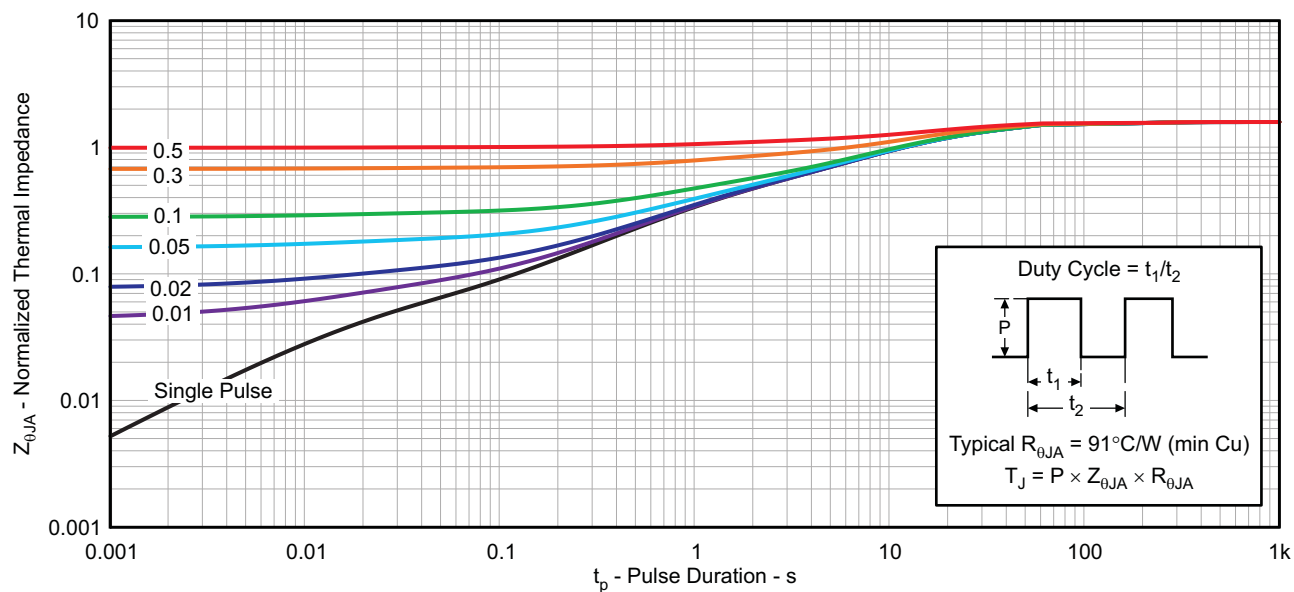
M0137-01



M0137-02

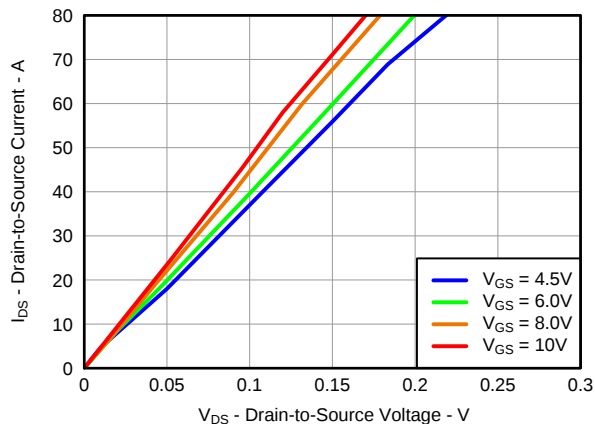
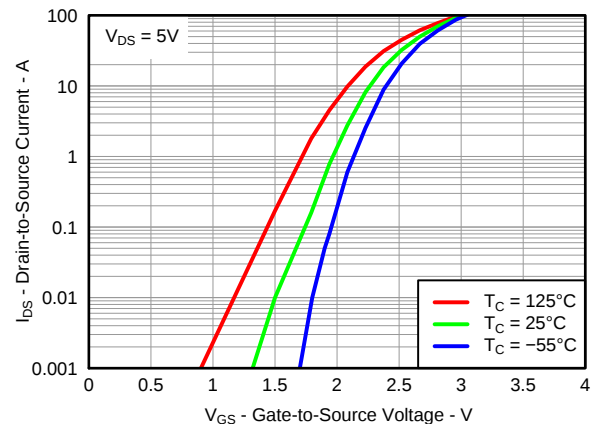
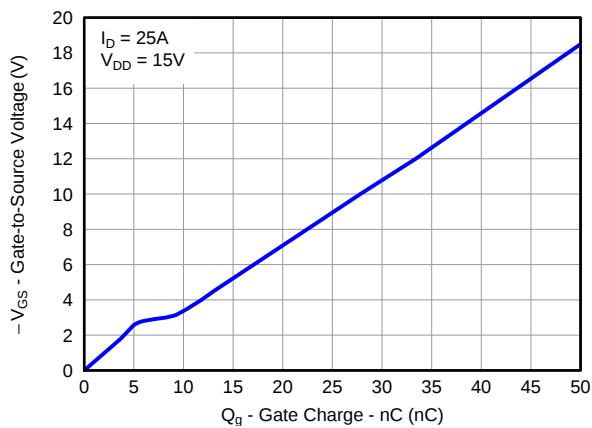
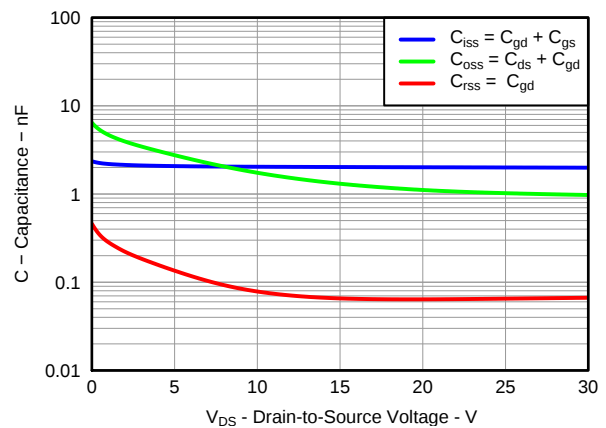
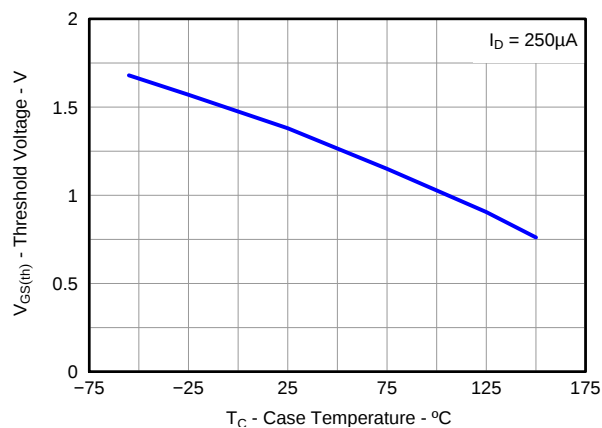
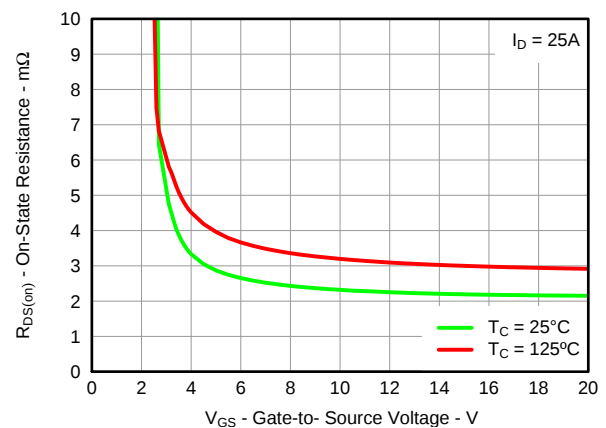
TYPICAL MOSFET CHARACTERISTICS

($T_A = 25^{\circ}\text{C}$ unless otherwise stated)



G012

Figure 1. Transient Thermal Impedance

TYPICAL MOSFET CHARACTERISTICS (continued)(T_A = 25°C unless otherwise stated)**Figure 2. Saturation Characteristics****Figure 3. Transfer Characteristics****Figure 4. Gate Charge****Figure 5. Capacitance****Figure 6. Threshold Voltage vs. Temperature****Figure 7. On-State Resistance vs. Gate-to-Source Voltage**

TYPICAL MOSFET CHARACTERISTICS (continued)

($T_A = 25^\circ\text{C}$ unless otherwise stated)

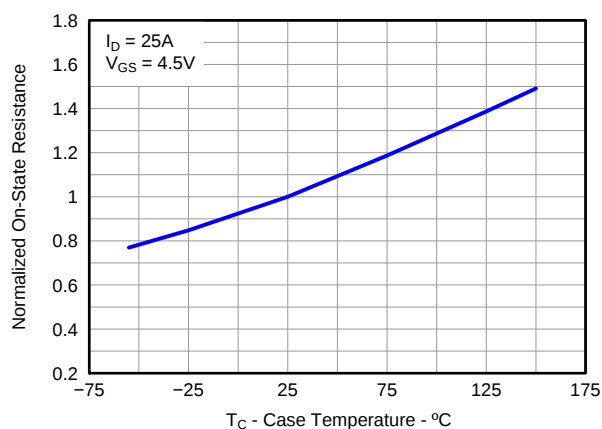


Figure 8. Normalized On-State Resistance vs. Temperature

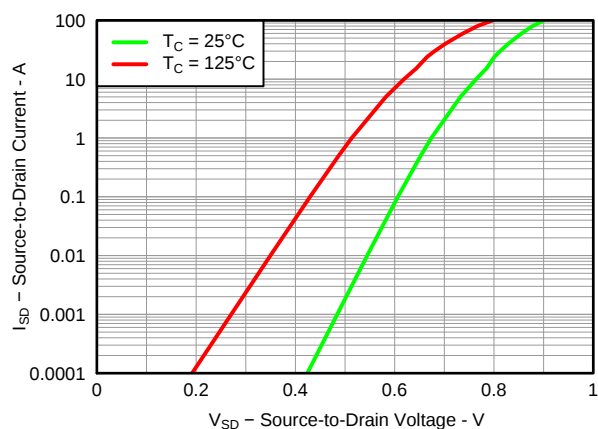


Figure 9. Typical Diode Forward Voltage

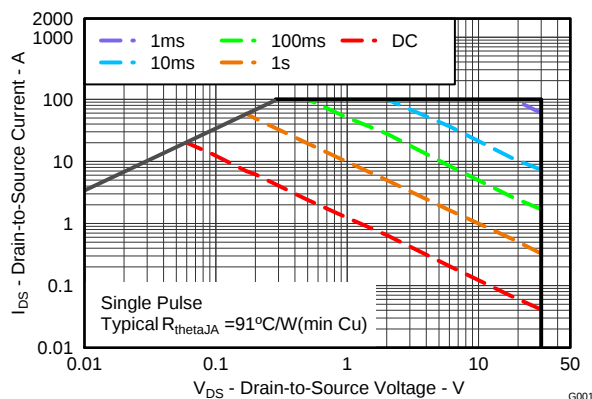


Figure 10. Maximum Safe Operating Area

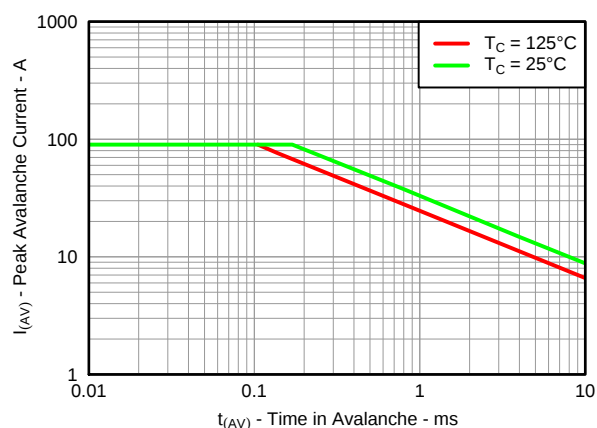


Figure 11. Single Pulse Unclamped Inductive Switching

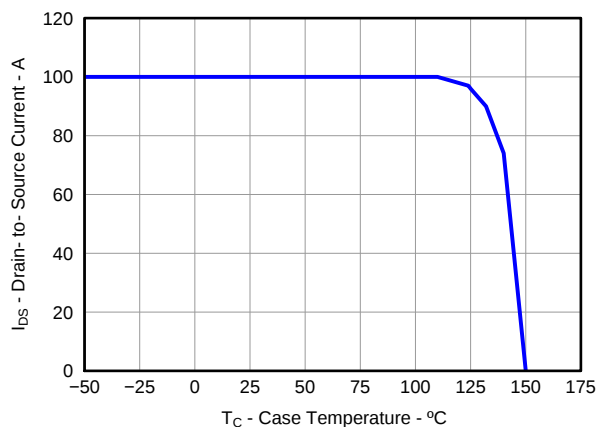
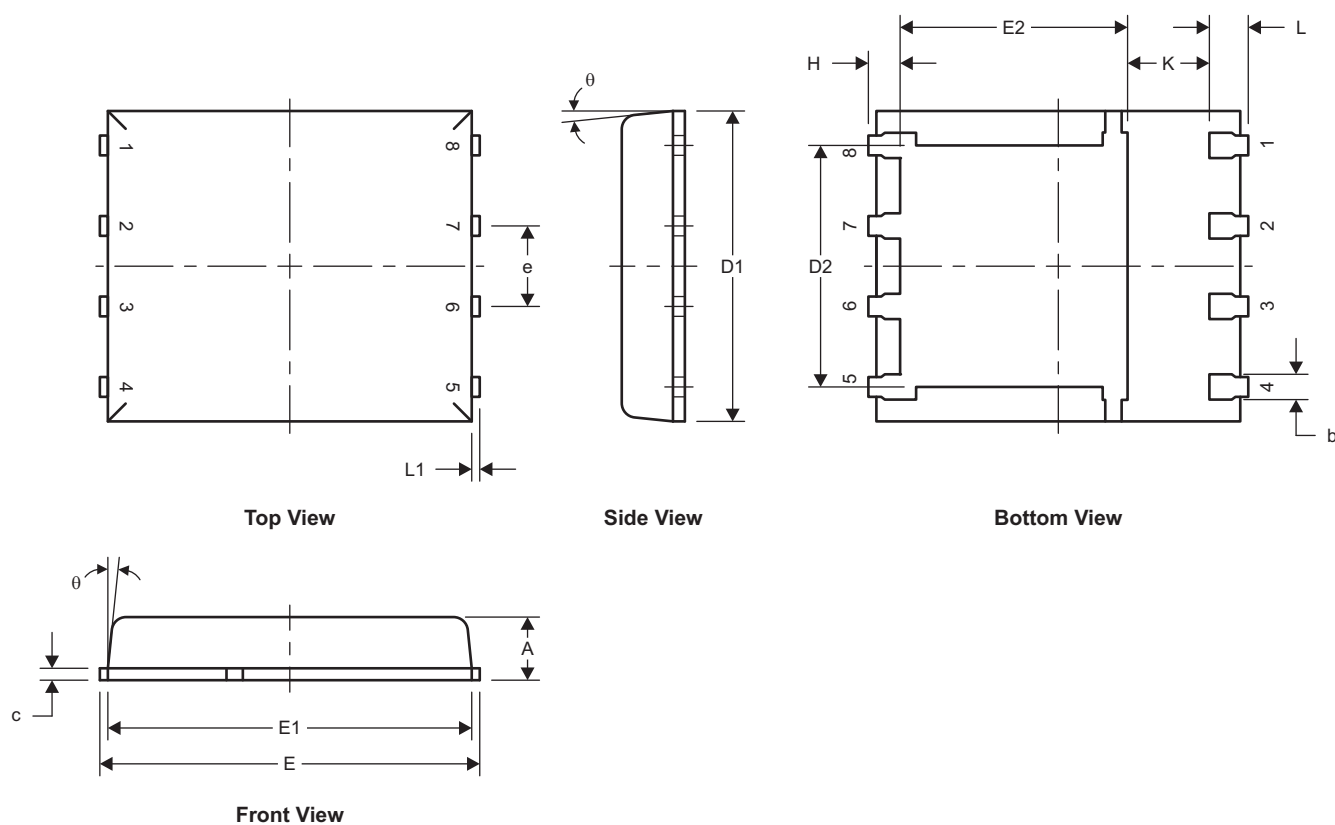


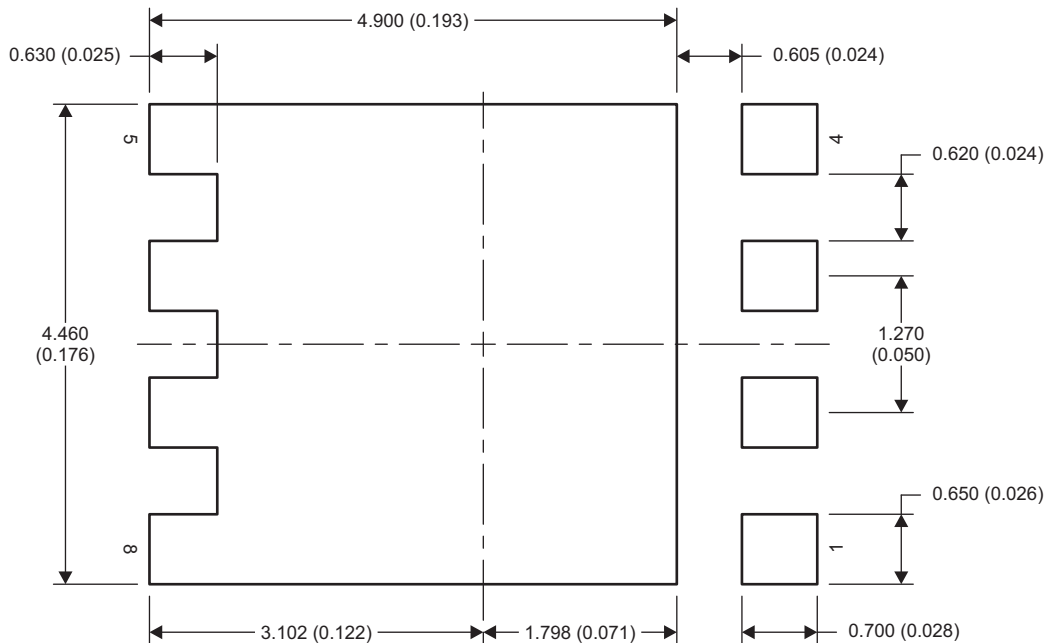
Figure 12. Maximum Drain Current vs. Temperature

MECHANICAL DATA**Q5A Package Dimensions**

M0135-01

DIM	MILLIMETERS		
	MIN	NOM	MAX
A	0.90	1.00	1.10
b	0.33	0.41	0.51
c	0.20	0.25	0.34
D1	4.80	4.90	5.00
D2	3.61	3.81	4.02
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.17	1.27	1.37
H	0.41	0.56	0.71
K	1.10		
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
θ	0°		12°

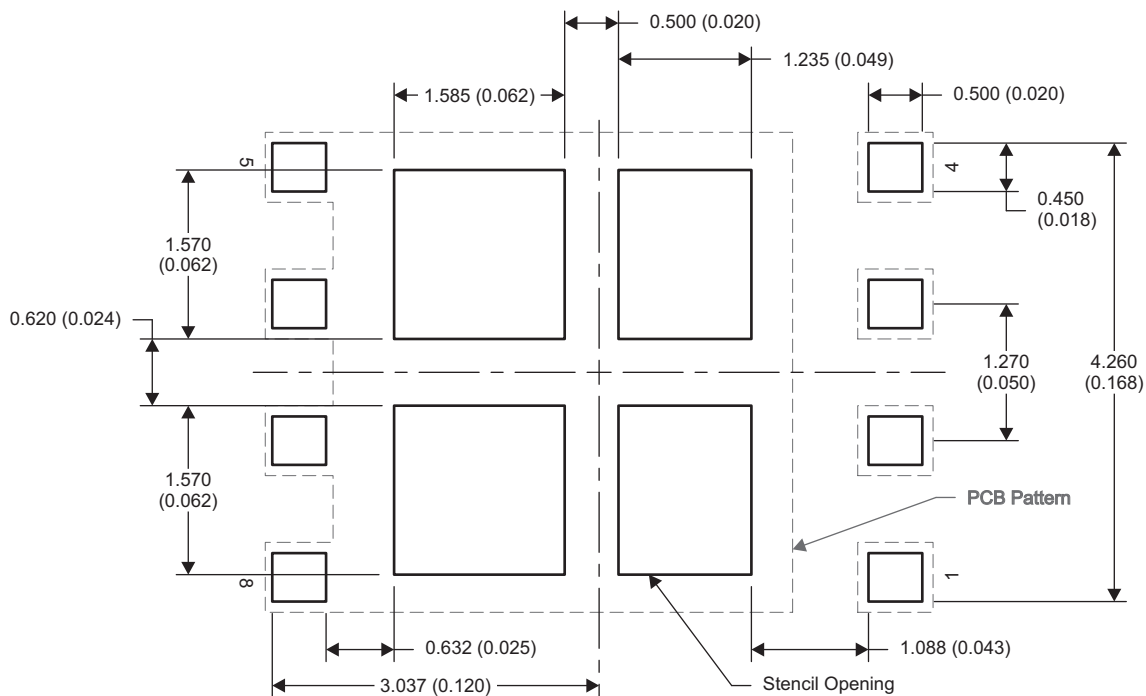
Recommended PCB Pattern



M0139-01

NOTE: Dimensions are in mm (inches).

Stencil Recommendation

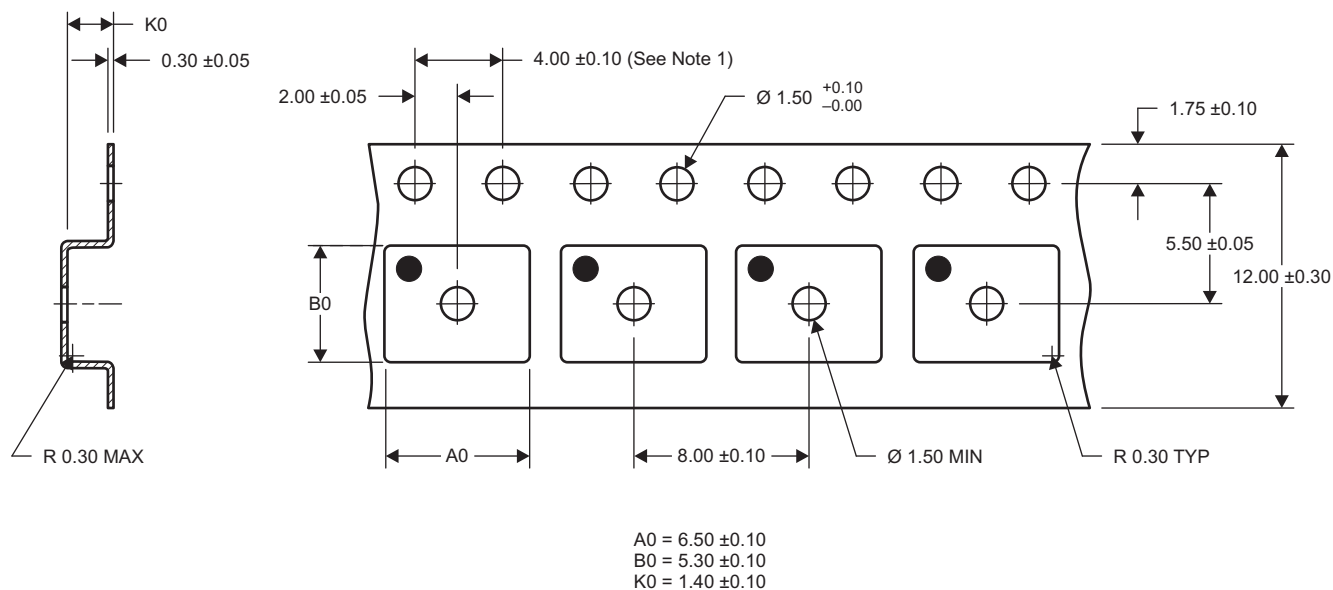


M0209-01

NOTE: Dimensions are in mm (inches).

For recommended circuit layout for PCB designs, see application note [SLPA005](#) – *Reducing Ringing Through PCB Layout Techniques*.

Q5A Tape and Reel Information



M0138-01

- NOTES:
- 10-sprocket hole-pitch cumulative tolerance ± 0.2
 - Camber not to exceed 1mm in 100mm, noncumulative over 250mm
 - Material: black static-dissipative polystyrene
 - All dimensions are in mm (unless otherwise specified)
 - A0 and B0 measured on a plane 0.3mm above the bottom of the pocket

REVISION HISTORY

Changes from Original (December 2010) to Revision A	Page
• Changed V_{GS} in the Abs Max Ratings table From: +20/-12V To: $\pm 20V$	1
• Changed the I_{GSS} Test Conditions From: $V_{GS} = 20V$ +20/-12 To: $V_{GS} = 20V$	2
Changes from Revision A (July 2011) to Revision B	Page
• Changed Figure 10	5

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
CSD17501Q5A	Active	Production	VSONP (DQJ) 8	2500 LARGE T&R	ROHS Exempt	SN	Level-1-260C-UNLIM	-55 to 150	CSD17501
CSD17501Q5A.B	Active	Production	VSONP (DQJ) 8	2500 LARGE T&R	ROHS Exempt	SN	Level-1-260C-UNLIM	-55 to 150	CSD17501

- ⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).
- ⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.
- ⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.
- ⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- ⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- ⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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